



Schedule of Scope to Certificate of Approval Independent Testing Laboratory

IECQ Certificate No.: IECQ-L DEKRA 16.0002-02

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Environmental and Reliability Testing of Electronic Components, Assemblies, and Related Materials

Description test	Standard
Steady-Status Temperature and Humidity Bias Life Test (THB)	JESD22-A101, AEC-Q100, AECQ-101, AEC-Q200, MIL-STD-202
High Humidity High Temp. Reverse Bias (H3TRB)	JESD22-A101, AEC-Q101
Power and Temperature Cycling (PTC)	JESD22-A105, AEC-Q100, AEC-Q101
High Temperature Operation test (HTOL)	JESD22-A108, AEC-Q100, AEC-Q200, MIL-STD-202
Low Temperature Operation test (LTOL)	JESD22-A108
High Temperature Reverse Bias (HTRB)	JESD22-A108, AEC-Q101, MIL-STD-750, MIL-STD-883
High Temperature Gate Bias (HTGB)	JESD22-A108, AEC-Q101
Early Life Failure Rate (ELFR)	JESD22-A108, AEC-Q100
Highly Accelerated Stress Test (HAST)	JESD22-A110, AEC-Q100, AEC-Q101
Electrically Erasable Programmable ROM (EEPROM) Program/Erase Endurance and Data Retention Stress Test (Endurance and Data Retention)	JESD22-A117, AEC-Q100,
Power Cycling	JESD22-A122
NVM Endurance, Data Retention, and Operation Life (EDR)	AEC-Q100
Electromigration (EM)	JEP001, JESD61, JESD87, AEC-Q100,
Stress Migration (SM)	JEP001, JEP139, JESD87, AEC-Q100,
Steady-Status operation life	MIL-STD-750, MIL-STD-883
Wafer/Substrate saw	A00-550-30001
Die Bond	A00-550-30034
Wire Bonding	A00-550-30003 A00-550-30035

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